

Product Change Notice

Issue Date: July 22, 2020

Change Type:

Add Assembly Production Site – ASE Taiwan

Parts Affected:

BCM53570B0IFSBG
BCM53570B0KFSBG
BCM53575B0IFSBG
BCM53575B0KFSBG
BCM56170B0IFSBG
BCM56170B0KFSBG
BCM56172B0IFSBG
BCM56172B0KFSBG
BCM56174B0IFSBG
BCM56174B0KFSBG

Description and Extent of Change:

Add ASE Taiwan as the assembly supplier for the above device

Reasons for Change:

Supply Chain manufacturing flexibility and capacity

Effect of Change on Fit, Form, Function, Quality, or Reliability:

There will be no change in fit, form, function, quality or reliability

Effective Date of Change:

October 22, 2020

Qualification Data:

Package Qualification Reference#: 004487
 Fab Technology: 28nm
 Package Type: FCBGA+HS
 Package Size: 35 x 35
 Lead Count: 1413

Stress Test	Condition	Read points	Sample Size	Requirements	Results (# fail/ss)
		Cycles / Hrs.			
Precondition	MSL3 JESD22-A113E		154 units	0 failures	0 / 154
Temp Cycle	-55°C / 125°C JEDEC Std. 22-A104-C Cond. B	1000 cycles	77 units	0 failures	0 / 77
uHast	130°C/85%RH JEDEC Std. 22-A102-C	96hrs	77 units	0 failures	0 / 77
HTSL	TA=150°C	1000hrs	77 units	0 failures	0 / 77

Please contact your Broadcom field sales engineer or Contact Center for any questions or support requirements. Please return any response as soon as possible, but not to exceed 30 days.